

ABSTRACT OF THE INVENTION

[0112] The present invention includes a method that provides a first wafer; forms a first raised contact from a first plug on the first wafer; provides a second wafer; forms a second raised contact from a second plug on the second wafer; applies an anisotropic conductive adhesive over the first wafer; aligns the second wafer to the first wafer; attaches the second wafer to the anisotropic conductive adhesive to form a continuous and conductive path between the first raised contact and the second raised contact.

[0113] The present invention also includes a structure that has an anisotropic conductive film, the anisotropic conductive film has a front surface and a rear surface; a first raised contact is located over the front surface, the first raised contact forming part of a first wafer; and a second raised contact located over the rear surface, the second raised contact forming part of a second wafer, where the second raised contact faces the first raised contact.